

AF

10/532543

PATENT ABSTRACTS OF JAPAN

IC20 Rec'd PCT/PTO 22 APR 2005

(11)Publication number : 11-256262

(43)Date of publication of application : 21.09.1999

(51)Int.Cl.

C22C 27/04

C22C 32/00

(21)Application number : 10-054884

(71)Applicant : MITSUBISHI MATERIALS CORP

(22)Date of filing : 06.03.1998

(72)Inventor : MOCHIDA HIROMI
YOSHITAKE SHUNICHI
TANAKA MICHIIRO

(54) TUNGSTEN ELECTRODE MATERIAL

(57)Abstract:

PROBLEM TO BE SOLVED: To make the arc ignitibility and resistance to consumption of a material excellent even under a high output and to make it the safe one free from radioactive contamination by incorporating a scandium compd. as an assistant component into tungsten as a main component.

SOLUTION: This electrode material contains a scandium compd. as an assistant component and the balance substantially consists of tungsten as a main component. The scandium compd. is composed of Sc_2O_3 , ScF_3 or the like and its content is preferably made to 0.02 to 5 wt.%. As the tungsten powder and scandium compd. powder as the raw material powder, the ones having 0.5 to 20 μm average particle size are preferably used. This tungsten electrode material is obtd. by adding scandium fluoride powder or scandium oxide powder having 1 μm average particle size to the tungsten powder having about 1 to 5 μm average particle size, stirring and mixing them in a dry process till they are uniformly dispersed, subjecting the obtd. powdery mixture to cold press molding and successively executing sintering or the like.

LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

USPS EXPRESS MAIL

EV 511 024 386 US

APRIL 22 2005

Copyright (C); 1998,2003 Japan Patent Office